PCN Number:		PCN20130904000						PCN Date:	09/05/2013				
Title: Aizu Facility			as an additional FAB source for select devices in the F05 Process										
<b>Customer Contact:</b>			PCN Manager Ph			Phone	e: +1(214)480	)-60	037	<b>Dept:</b> Quality Services			
Proposed 1 <sup>st</sup> Ship Date:			1 1 //115/ /111 3				Estimated Sample Availability:			Date provided at sample request.			
Chan	ige T	ype:											
	Asse	Assembly Proces				SS		ssembly Materia	y Materials				
	Desi						Specification			Mechanical Specification			
		Site					hipping/Labeling			Test Process			
		er Bump Site		<u> </u>		mp Material			_	Wafer Bump Process			
		☐ Wafer Fab Materials			Ш	W	afer Fab Proces	SS					
			☐ Part number change										
				PCN Details									
Desc	riptio	on of Change	<b>:</b>										
This notification is to announce AIZU fabrication facility as an additional wafer FAB source for select devices in the F05 Process. The affected devices are listed in "Product Affected" section.										on.			
		Qualified Site Process, 200			ess, water	Dia.	Additional Site, Process, Wafer Dia.  AIZU, F05 Process, 200mm						
The F05 process was qualified in Aizu in June 2012. Qualification details are provided in the Qual Data Section.								in the Qual					
Reas	on fo	r Change:											
Continuity of Supply													
Antic	ipate	ed impact or	Fo	rm	, Fit, Funct	ion, Q	uality or Relia	bil	ity	(positive / ne	gative):		
None													
Changes to product identification resulting from this PCN:													
Current Chip Site Chip site code (20L) Chip country code (21L)													
DP1DM5		DM5			.,	USA							
Addit	tional	10110			D113								
	Chip Site			ip s	ite code (20L	.)	Chip country code (21L)						
AIZU		CU2			JPN								
Sample product shipping label (not actual product label)													
TEXAS INSTRUMENTS  MADE IN: Malaysia 2DC: 2Q:  MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04  OPT: ITEM: 39  LBL: 5A (L)T0: 1750  (1P) \$N74L\$07N\$R  (Q) 2000 (D) 0336  (31T) LOT: 3959047MLA  (4W) TKY(1T) 7523483\$I2  (P) (2P) MEV: (V) 0033317  (20L) CSO: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ASO: MYS													

Product Affected:							
SM02028APTT	TMS320F28021PTT	TMS320F28023DAT	TMS320F280270DAT				
SM28020PTT	TMS320F280220DAS	TMS320F28023PTS	TMS320F280270PTS				
SM28021PTT	TMS320F280220DAT	TMS320F28023PTT	TMS320F280270PTT				
TJF026PTT	TMS320F280220PTS	TMS320F280260DAS	TMS320F28027DAS				
TMS320F280200DAS	TMS320F280220PTT	TMS320F280260DAT	TMS320F28027DASR				
TMS320F280200DAT	TMS320F28022DAS	TMS320F280260PTS	TMS320F28027DAT				
TMS320F280200PTS	TMS320F28022DAT	TMS320F280260PTT	TMS320F28027DATR				
TMS320F280200PTT	TMS320F28022PTS	TMS320F28026DAS	TMS320F28027FPTT				
TMS320F28020DAS	TMS320F28022PTSR	TMS320F28026DASR	TMS320F28027PTR				
TMS320F28020DAT	TMS320F28022PTT	TMS320F28026DAT	TMS320F28027PTS				
TMS320F28020PTS	TMS320F280230DAS	TMS320F28026DATR	TMS320F28027PTT				
TMS320F28020PTT	TMS320F280230DAT	TMS320F28026FPTT	TMS320F28KNWMX1				
TMS320F28021DAS	TMS320F280230PTS	TMS320F28026PTS	TMS320SPC0200PTT				
TMS320F28021DAT	TMS320F280230PTT	TMS320F28026PTT					
TMS320F28021PTS	TMS320F28023DAS	TMS320F280270DAS					

Qualification Data: Approved 8/30/2013									
This qualification has been developed for the validation of this change. The qualification data will									
validate that the proposed change meets the applicable released technical specifications.									
	Qual Vehicle 1: TMS320F2802XAPT								
Wafer Fab Site	: AIZU		Metallization:	Metallization: TiN/AlCu/TiN					
Wafer Fab Process: F05 Wafer diameter: 200mm									
Qualification:   Plan   Test Results									
Reliability Test Conditions Sample Si						•	· · ·		
,					Lot#1	Lot#2	Lot#3		
	MSL2/26				540/0	-	-		
*Temp Cycle	·65C/15	0C 5	00 Cycles (actual :	1000 cycles)	231/0	-	-		
*Autoclave 121C/96			(actual 168 hours)	231/0	-	-			
Notes: * Test requires Moisture Preconditioning									
Qualification tests "pass" on zero fails for each test									
Qual Vehicle 2: TMS320F2802XADA									
Wafer Fab Site: AIZU Metallization: TiN/AlCu/TiN									
Wafer Fab Process: F05 Wafer diameter: 200mm									
Qualification:									
Reliability Test Conditions Sample Size/Fail						-			
Lot#1 Lot#2 Lot#3						Lot#3			
Preconditioning MSL2/260C 720/0						-			
*Temp Cycle	65C/150C 500 Cycles(actual 750 cycles)				231/0	-	-		
*Autoclave 121C/96hr			(actual 168 hours)	231/0	-	-			
*High Temp Storage Life	150C, 5	500 hours			231/0	-	-		
ESD-HBM 2000v					3/0	-	-		
ESD-CDM	750v			3/0	-	-			
Latchup	1.5Vdd	+/-1	/-100mA 125C 6/0						
Notes: * Test requires Moisture Preconditioning									
Qualification tests "pass" on zero fails for each test									

## Reference Qual: F05 Process Qualification at Aizu

Qualification Data: Approved 06/2012								
This qualification has been developed for the validation of this change. The qualification data will								
validate that the proposed change meets the applicable released technical specifications.								
Qual Vehicle 1: TMS320F2803XAPN								
Wafer Fab Site:	AIZU	IZU Metallization: TiN/AlCu/TiN						
Wafer Fab Process:	F05	Wafer diameter: 200mm						
Qualification:   Plan   Test Results								
Reliability Test	Conditi	Conditions			Sample Size/Fail			
Reliability Test	Condici				Lot#2	Lot#3		
20K W/E		20K Write / Erase Cycles prior to HTSL, HTOL, RTSL			-	-		
High Temperature Op Life	125C - 1	125C - 1000 Hours			-	-		
*High Temp Storage Life	150C Ba	150C Bake - 1000 Hours			-	-		
Room Temp Storage Life	25C - 1	25C - 1000 Hours			-	-		
Package Reliability					-	-		
*Preconditioning	MSL3/2	MSL3/260C			-	-		
*THB	85C/85I	85C/85RH			-	-		
*Temp Cycle	-65C/150C 500 Cycles			231/0	-	-		
*Autoclave	121C/9	121C/96hrs			-	-		
ESD-HBM	2000v				-	-		
ESD-CDM	750v	750v			-	_		
Latch up	1.5Vdd	1.5Vdd +/-100mA 125C			-	-		
Notes: * Test requires Moisture Preconditioning								
Qualification tests "pass" on zero fails for each test								

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com